

Features

- Glass passivated fast recovery rectifiers
- Ideal for automated placement
- Low forward voltage drop
- High current capability
- Low reverse leakage current
- Solder dip 260 °C, 10s
- Solderability 245°C, 5sec.
- Moisture sensitivity: level 1, per J-STD-020



DO-214AC (SMA)

Applications

For use of fast switching rectification in lighting, cellular phone, portable device, power supplies and other consumer applications.

Maximum Ratings ($T_A=25$ °C unless otherwise noted)

Parameter	Symbol	GROAA	GROBA	GRODA	GROGA	GROJA	GROKA	GROMA	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$				1.5				A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed On Rated Load	I_{FSM}				50				A
Storage Temperature Range	T_{STG}				- 55 to + 150				°C
Operating Junction Temperature Range	T_J				- 55 to + 150				°C

Electrical Characteristics ($T_A=25$ °C unless otherwise noted)

Parameter	Test Conditions	Symbol	GROAA	GROBA	GRODA	GROGA	GROJA	GROKA	GROMA	Unit
Maximum Instantaneous Forward Voltage	1.5A	V_F				1.3				V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$	I_R			5					μA
	$T_A=125^\circ\text{C}$	I_R			200					
Maximum Reverse Recovery Time	$I_F=0.5\text{A}, I_R=1.0\text{A}, t_{rr}=0.25\text{A}$	t_{rr}		150		250		500		nS
Typical Junction Capacitance	4.0 V, 1 MHz	C_J			11					pF
Typical Thermal Resistance ¹	Junction to Ambient	$R_{\theta JA}$			55					°C/W
	Junction to Lead	$R_{\theta JL}$			18					
	Junction to Case	$R_{\theta JC}$			30					

Note:

1. The thermal resistance from junction to lead, mounted on P.C.B with 5×5mm copper pads, 2 OZ, FR4 PCB

Ratings and Characteristics Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

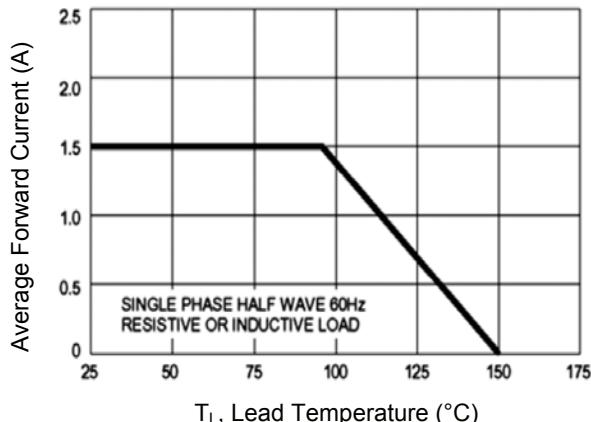


Figure 1. Forward Current Derating Curve

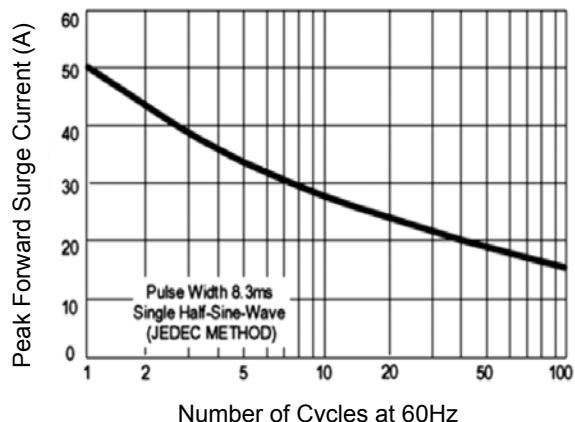


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

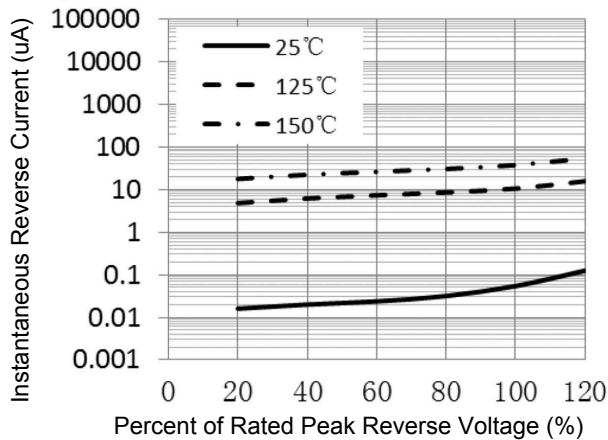


Figure 3. Typical Reverse Characteristics

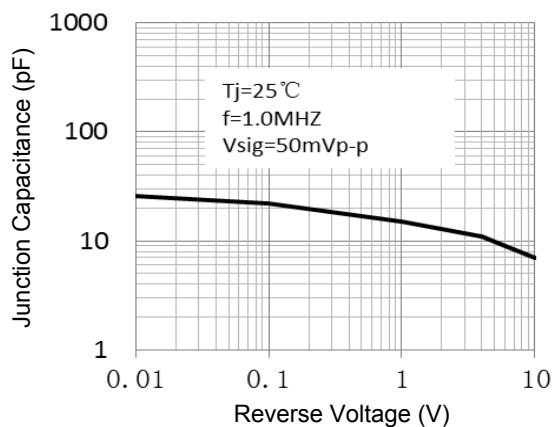


Figure 4. Typical Junction Capacitance

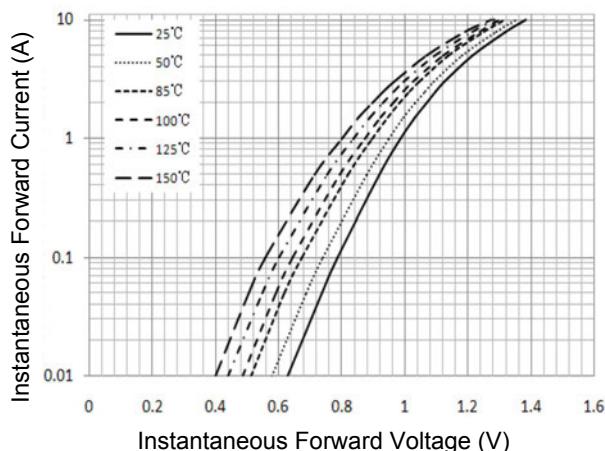
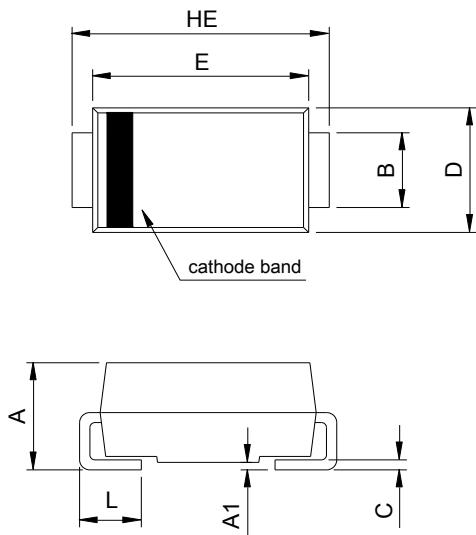


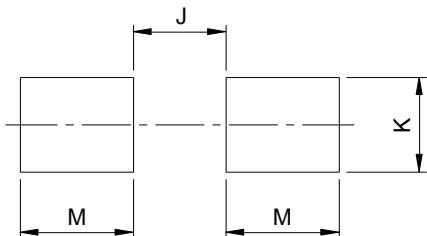
Figure 5. Typical Instantaneous Forward Characteristics

Package Outline Dimensions DO-214AC (SMA)



SMA (DO-214AC)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.90	2.30	0.075	0.091
A1	0.00	0.20	0.000	0.008
B	1.25	1.65	0.049	0.065
C	0.15	0.31	0.006	0.012
D	2.35	2.90	0.093	0.114
E	3.99	4.60	0.157	0.181
HE	4.80	5.30	0.189	0.209
L	0.76	1.52	0.030	0.060

Recommended Pad Layout



Recommended Pad Layout (Reference ONLY)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.20	-	0.087
K	1.72	-	0.068	-
M	2.00	-	0.079	-